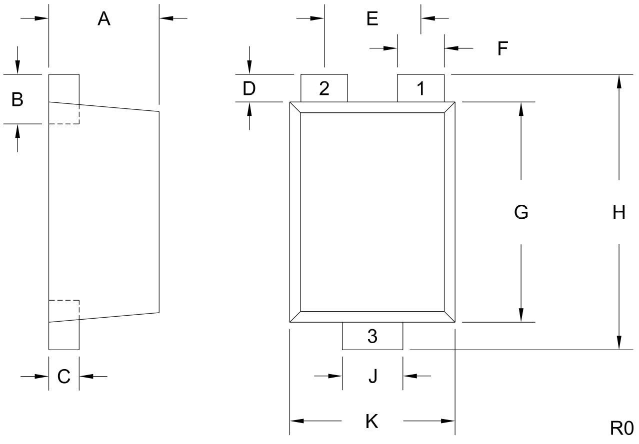
Package Details

SOT-923 Case

Central Semiconductor Corp.

Mechanical Drawing



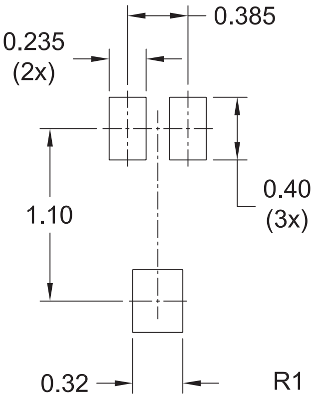
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.015	0.016	0.39	0.41
B	0.004	0.010	0.10	0.26
C	0.003	0.006	0.08	0.14
D	0.002	0.006	0.05	0.15
E	0.014		0.35	
F	0.005	0.009	0.12	0.22
G	0.030	0.033	0.75	0.85
H	0.035	0.043	0.90	1.10
J	0.007	0.011	0.17	0.27
K	0.022	0.026	0.55	0.65

SOT-923 (REV: R0)

Lead Code:
Reference individual
device datasheet.

Part Marking: Single Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



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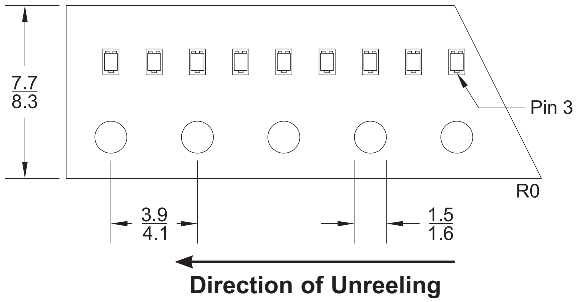
Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in
accordance with
Electronic Industries
Association Standard
EIA-481-1-A

Packaging Base

7” Reel = 8,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

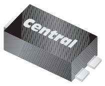
Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (4-March 2010)

Material Composition Specification

SOT-923 Case



Device average mass . . . . **0.45 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	6.67%	0.07	Si	7440-21-3	6.67%	0.03	66,667
bond wire	gold	0.67%	0.003	Au	7440-57-5	0.67%	0.003	6,667
leadframe	copper w/ silver plating	47.78%	0.215	Cu	7440-50-8	46.67%	0.21	466,667
				Ag	7440-22-4	1.11%	0.005	11,111
encapsulation*	EMC	42.67%	0.192	silica	7631-86-9	30.67%	0.138	306,667
				epoxy resin	Proprietary	10.67%	0.048	106,667
				Sb_2O_3	1309-64-4	0.89%	0.004	8,889
				TBBA	79-94-7	0.22%	0.001	2,222
				carbon black	1333-86-4	0.22%	0.001	2,222
	EMC GREEN	42.67%	0.192	silica	60676-86-0	28.22%	0.127	282,222
				epoxy resin	29690-82-2	4.89%	0.022	48,889
				phenol resin	9003-35-4	4.89%	0.022	48,889
				carbon black	1333-86-4	0.22%	0.001	2,222
				metal hydroxide	1309-42-8	4.44%	0.02	44,444
plating	matte tin	2.22%	0.01	Sn	7440-31-5	2.22%	0.01	22,222

*EMC GREEN molding compound is Halogen-Free.

R2 (23-January 2014)